

Receipt
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JUL 30 2002 IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

O I P E
PATENT & TRADEMARK OFFICE
In re PATENT application of)
Osamu NAKAMURA et al.)
Serial No. 10/056,055)
Filed: January 28, 2002)
For: SEMICONDUCTOR DEVICE AND)
MANUFACTURING METHOD OF)
THE SAME)

Attn: Customer Correction Branch

FILE COPY

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6-11-03
Rework

CERTIFICATE OF MAILING

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Attention: Application Processing Division

REQUEST FOR CORRECTED FILING RECEIPT

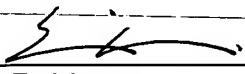
Honorable Commissioner of Patents
Washington, D.C. 20231

Sir:

The Filing Receipt received in the above-identified application has errors thereon
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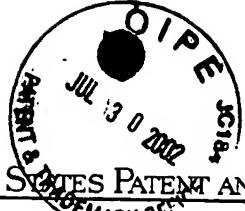
In view of the above, it is requested that a Corrected Filing Receipt be issued.

Respectfully submitted,


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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	TO 2622	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS	www.uspto.gov
10/056,055	01/28/2002	2811	2622	0756-2428	24	80	11	

31780
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CONFIRMATION NO. 3986

UPDATED FILING RECEIPT



OC000000008176732

Date Mailed: 05/23/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

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JAPAN 2001-019367 01/29/2001

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N n-Publication Request: No

Early Publication Request: No

Title

Semiconductor device and manufacturing method of the same